



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
* : Required Field			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-05-21
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD Champion
Representative Phone *	Refer to Supplier Comment section		Refer to Supplier Comment section
Representative Email *	Refer to Supplier Comment section		
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	HZDF*UI25AA5	A	SHENZHEN B/E	2015-05-21
Amount	UoM	Unit type	ST ECOPACK Grade	
290.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	225	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	6.5, 6.1, 2.3	3	GULL WING	
Comment	TO 252 DPAK AU BONDING WIRES; MD valid for CP :LDFM50DT-TR.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2014				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HZDF*UI25AA5					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	0.781	mg	supplier	die	Silicon (Si)	7440-21-3		0.712	mg	911765	2459
				supplier	metallization	Aluminium (Al)	7429-90-5		0.007	mg	8951	24
				supplier	metallization	Tungsten (W)	7440-33-7		0.010	mg	12788	34
Leadframe	Copper & its alloys	164.944	mg	supplier	Passivation	Silicon Oxide	7631-86-9		0.052	mg	66496	179
				supplier	alloy	Copper (Cu)	7440-50-8		164.152	mg	995198	566041
				supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.330	mg	2001	1138
Soft solder	Solder	0.842	mg	supplier	alloy	Cobalt (Co)	7440-48-4		0.462	mg	2801	1593
				JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	0.804	mg	954869	2772
				supplier	solder	Silver (Ag)	7440-22-4		0.021	mg	24941	72
Bonding wires	Other inorganic materials	0.264	mg	supplier	solder	Tin (Sn)	7440-31-5		0.017	mg	20190	59
				supplier	wire	Gold (Au)	7440-57-5		0.264	mg	1000000	910
Encapsulation	Other Organic Materials	122.124	mg	supplier	mold compound	Silica, vitreous	60676-86-0		106.858	mg	874996	368476
				supplier	mold compound	Tetramethyl-biphenyl-diyl-bis oxymethylene-b	EC 413-900-7		4.885	mg	40000	16845
				supplier	mold compound	Epoxy Resin	Proprietary		3.664	mg	30002	12634
				supplier	mold compound	phenol resin	Proprietary		6.106	mg	49998	21055
connections coating	Solder	1.045	mg	supplier	mold compound	Carbon black	1333-86-4		0.611	mg	5003	2107
				supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3603